



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2024-04-01
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G0B1KEU7 STM32G0B1KEU7TR	7CMG*467XXXZ	A	998Z	2024-04-01
Amount	UoM	Unit type	ST ECOPACK Grade	
49.38	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.55	32	flat	
Comment	Package : A0B8 UFQFPN 5X5X0.55 32L 0.5 MM PITCH 8202208			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7CMG*467XXXZ				6000002.0	999996.8				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.936	mg	#N/A	die	Silicon (Si)	7440-21-3		2.599	mg	885218	52631				
				#N/A	metallization	Aluminium (Al)	7429-90-5		0.016	mg	5450	324				
				#N/A	metallization	Copper (Cu)	7440-50-8		0.143	mg	48706	2896				
				#N/A	metallization	Tantalum (Ta)	7440-25-7		0.046	mg	15668	932				
				#N/A	metallization	Titanium (Ti)	7440-32-6		0.002	mg	681	41				
				#N/A	metallization	Tungsten (W)	7440-33-7		0.001	mg	341	20				
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	12262	729				
				#N/A	Passivation	Silicon Oxide	7631-86-9		0.093	mg	31676	1883				
				Glue Epoxy (EN4900GC)	M-011 Other inorganic materials	0.427	mg	Supplier	Organic Compounds	Acrylic resin	Proprietary		0.030	mg	70000	606
								Supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.009	mg	20000	173
Supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.006	mg	15000	130				
Supplier	Organic Compounds	Acrylate	Proprietary						0.023	mg	54000	467				
Supplier	Organic Compounds	Epoxy resin	Proprietary						0.013	mg	30000	260				
Supplier	Organic Compounds	Peroxide	Proprietary						0.003	mg	8000	69				
Supplier	Organic Compounds	Additive	Proprietary						0.008	mg	18000	156				
Supplier	Metals	Silver (Ag)	7440-22-4						0.335	mg	785000	6791				
Encapsulation (EME-G770)	M-011 Other inorganic materials	15.793	mg					Supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.332	mg	21000	6716
								Supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.332	mg	21000	6716
				Supplier	Organic Compounds	Phenol Resin A	Proprietary		0.332	mg	21000	6716				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		12.326	mg	780450	249605				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		1.821	mg	115320	36882				
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.098	mg	6230	1992				
				Supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.221	mg	14000	4477				
				Supplier	Organic Compounds	Phenol Resin B	Proprietary		0.332	mg	21000	6716				
				Bonding wire (Au)	Bonding Wire	0.306	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.306	mg	1000000	6192
				Plating (Sn)	M-011 Other inorganic materials	0.719	mg	Supplier	Metals	Tin (Sn)	7440-31-5		0.719	mg	1000000	14559
Leadframe (C7025 + Ag)	Copper & its alloys	29.200	mg	Supplier	Metals	Copper (Cu)	7440-50-8		26.780	mg	917140	542321				
				Supplier	Metals	Nickel (Ni)	7440-02-0		0.657	mg	22500	13305				
				Supplier	Metals	Silicon (Si)	7440-21-3		0.076	mg	2600	1537				
				Supplier	Metals	Magnesium (Mg)	7439-95-4		0.034	mg	1150	680				
				Supplier	Metals	Silver (Ag)	7440-22-4		1.653	mg	56610	33474				